

IV. AMENDMENTS TO THE CLAIMS

1. – 6. (CANCELED)

7. (NEW) A semiconductor device, comprising:

a semiconductor chip having a first semiconductor chip surface and a second semiconductor chip surface disposed opposite the first semiconductor chip surface, the second semiconductor chip surface defining a semiconductor chip surface area;

DI a wiring board having a wiring board thickness and being electrically connected to the semiconductor chip at the first semiconductor chip surface; and

a warp preventing board having a warp preventing board thickness and a warp preventing board surface defining a warp preventing board surface area,

wherein the warp preventing board surface and the second semiconductor chip surface are connected in face-to-face contact with each other so that the warp preventing board surface area of the warp preventing board surface covers the semiconductor chip surface area of the semiconductor chip, the warp preventing board thickness is substantially equal to the wiring board thickness and the warp preventing board and the wiring board are fabricated from an identical material.